

40V Dual N-Channel Enhancement Mode MOSFET

Description

The PECN4890SR uses advanced trench technology to provide excellent $R_{DS(ON)}$ with low gate charge.

This device is suitable for high side switch in SMPS and general purpose applications.

General Features

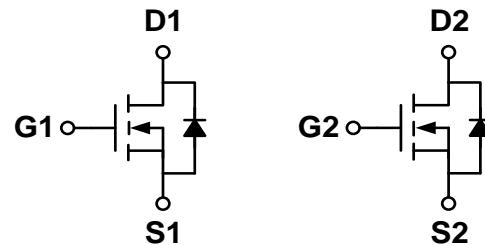
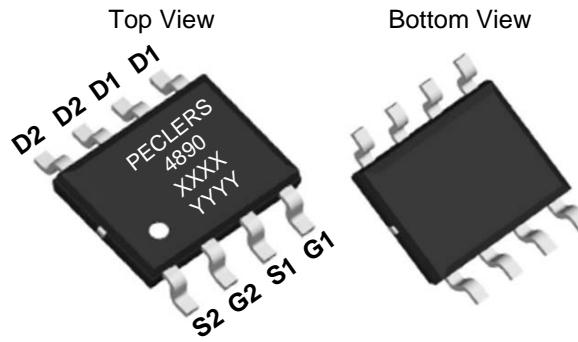
- ◆ $V_{DS} = 40V$, $ID = 12A$
 $R_{DS(ON)} = 9.7m\Omega$ (typical) @ $VGS = 10V$
 $R_{DS(ON)} = 11.4m\Omega$ (typical) @ $VGS = 4.5V$
- ◆ Excellent gate charge $\times R_{DS(ON)}$ product(FOM)
- ◆ Very low on-resistance $R_{DS(ON)}$
- ◆ 150 °C operating temperature
- ◆ Pb-free lead plating
- ◆ 100% UIS tested

Application

- ◆ DC/DC Converter
- ◆ Ideal for high-frequency switching and synchronous rectification

Package

- ◆ SOP-8

**Schematic diagram****Marking and pin assignment**

XXXX—Wafer Information

YYYY—Quality Code

Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
PECN4890SR	-55°C to +150°C	SOP-8	4000

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	V_{DS}	40	V
Gate-source voltage	V_{GS}	± 20	V
Drain Current-Continuous (Silicon Limited)	I_D	12	A
		8	
Pulsed Drain Current (Package Limited)	I_{DM}	48	A
Single pulse avalanche energy	E_{AS}	30	mJ
Maximum power dissipation	P_D	3	W
		2.1	
Operating junction Temperature range	T_j	-55—150	°C

Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	40	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =40V, V _{GS} =0V T _J =85°C	-	-	1	μA
			-	-	5	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1	1.5	2.3	V
Drain-source on-state resistance ¹	R _{DS(ON)}	V _{GS} =10V, I _D =12A	-	9.7	12	mΩ
		V _{GS} =4.5V, I _D =8A		11.4	15	
Forward Transconductance	g _{FS}	V _{DS} = 5V, I _D = 12A		60		S
Diode Characteristics						
Diode Forward Voltage	V _{SD}	I _{SD} =1A, V _{GS} =0V	-	0.82	1.1	V
Diode Continuous Forward Current	I _S		-	-	2.5	A
Reverse Recovery Time	t _{rr}	I _F =12A, dI/dt=100A/μs	-	30	-	ns
Reverse Recovery Charge	Q _{rr}		-	19	-	nC
Dynamic Characteristics						
Gate Resistance	R _G	V _{GS} =0V, V _{DS} =0V,f=1MHz	-	3.5	-	Ω
Input capacitance	C _{iss}	V _{GS} =0V ,V _{DS} =20V f=1.0MHz	-	2150	-	pF
Output capacitance	C _{oss}		-	123	-	
Reverse transfer capacitance	C _{rss}		-	153	-	
Turn-on delay time	t _{D(ON)}	V _{GS} =10V, V _{DS} =20V, R _L =2Ω, R _G =3Ω	-	6.4	-	ns
Turn-on Rise time	tr		-	17.2	-	
Turn-off delay time	t _{D(OFF)}		-	29.6	-	
Turn-off Fall time	t _f		-	16.8	-	
Total gate charge	Q _g	V _{GS} =10V, V _{DS} =20V,I _D =12A	-	37.9	-	nC
Gate-source charge	Q _{gs}			5.3		
Gate-drain charge	Q _{gd}		-	6.5	-	

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Maximum Junction-to-Ambient ^A	≤ 10s	R _{θJA}	33	40
Maximum Junction-to-Ambient ^A	Steady-State		59	75
Maximum Junction-to-Lead ^B	Steady-State		16	24

A: The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating.

B: The R_{θJA} is the sum of the thermal impedance from junction to lead R_{θJC} and lead to ambient.

Typical Performance Characteristics

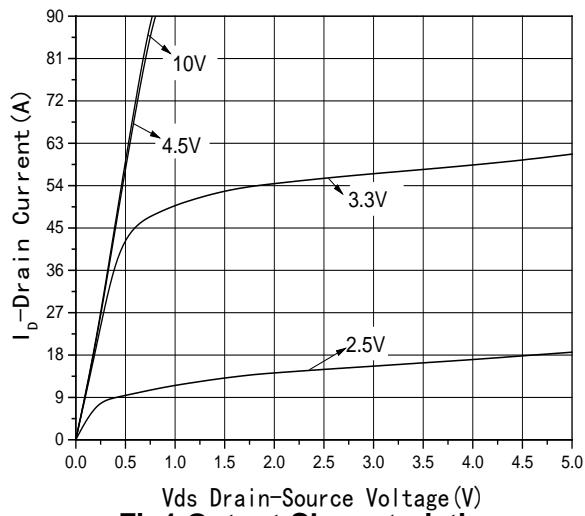


Fig1 Output Characteristics

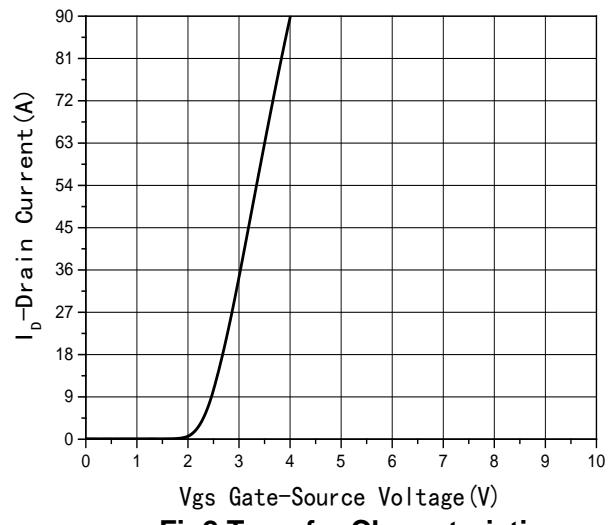


Fig2 Transfer Characteristics

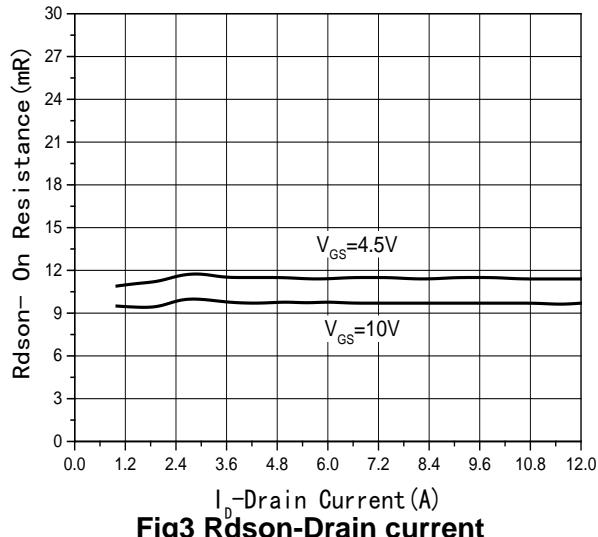


Fig3 Rdson-Drain current

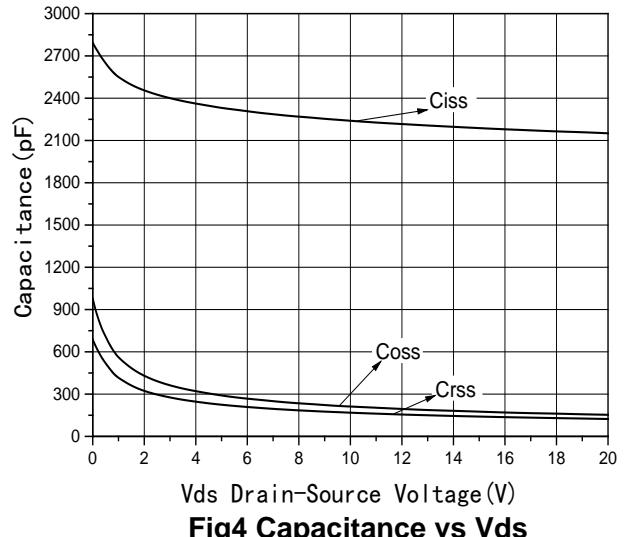


Fig4 Capacitance vs Vds

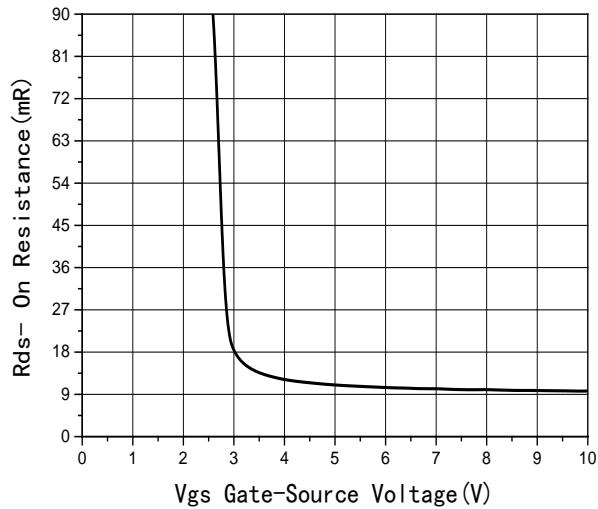


Fig5 Rdson-Gate Drain voltage

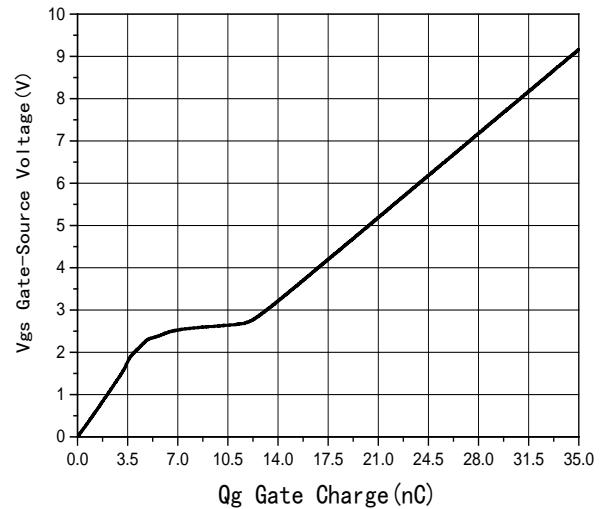


Fig6 Gate Charge

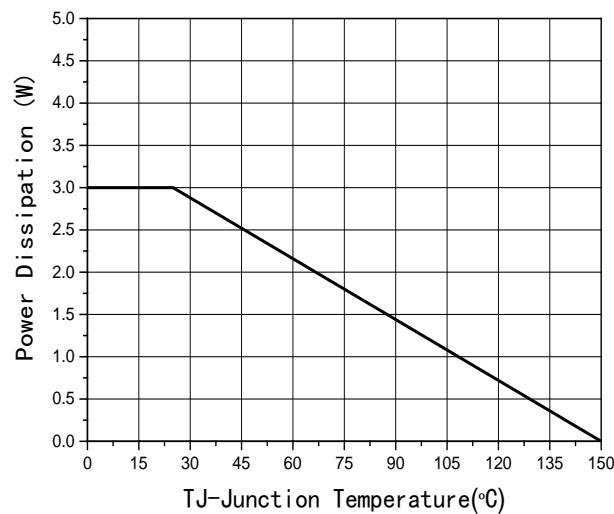


Fig7 Power De-rating

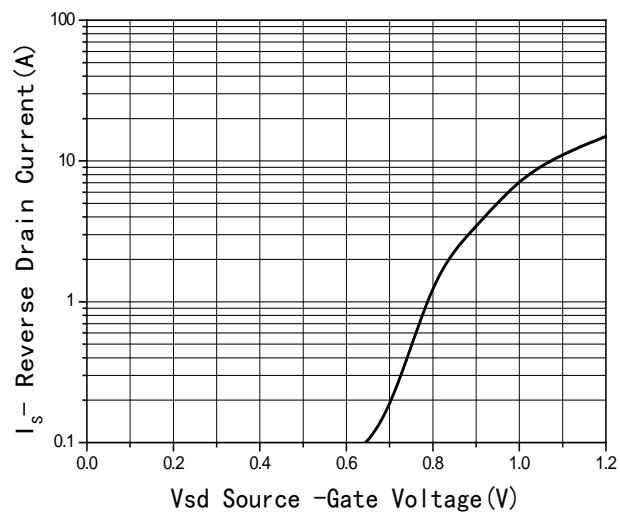
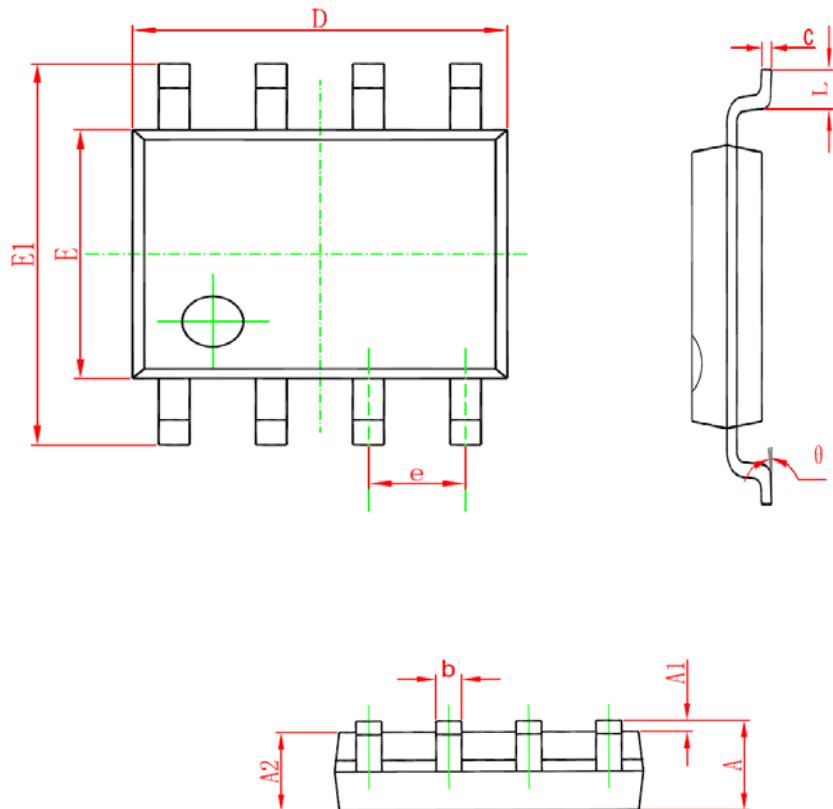


Fig8 Source-Drain Diode Forward

Package Information

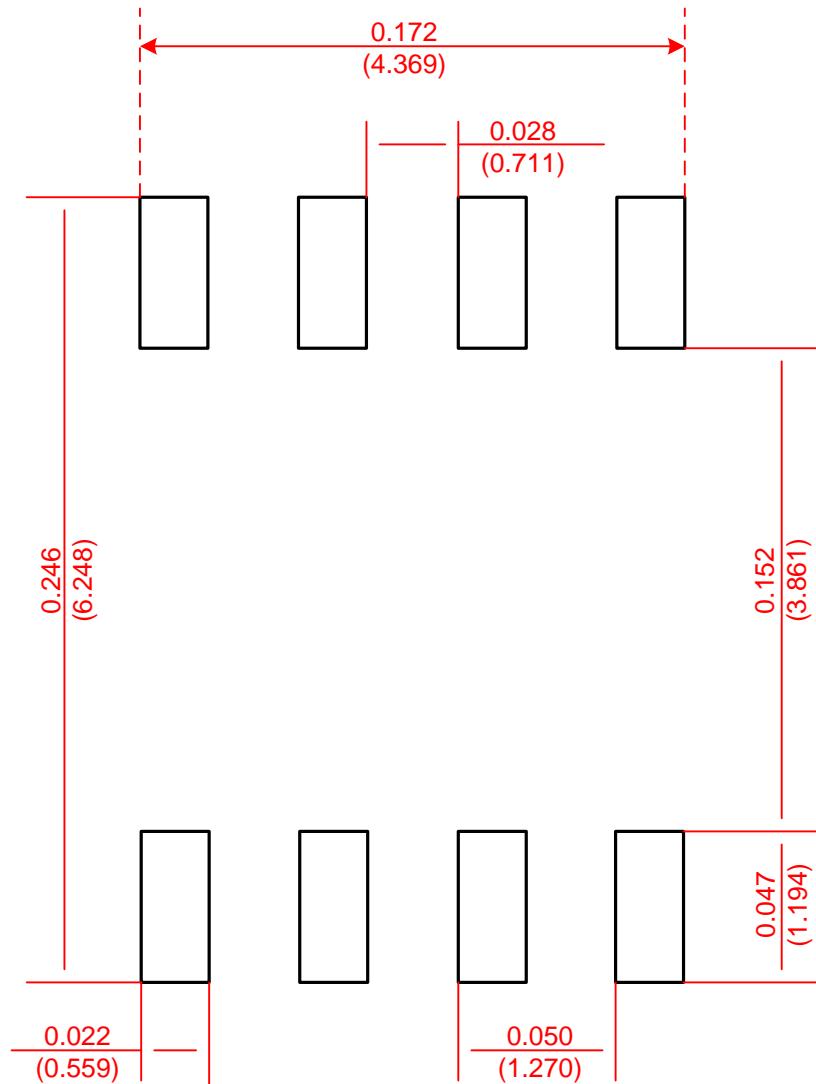
- SOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

Recommended Minimum Pads

- SOP-8



Recommended Minimum Pads
Dimensions in Inches/(mm)